

XENSIV™ PAS CO2 Datasheet



Description

Infineon has leveraged its knowledge in sensors and MEMS technologies to develop a disruptive gas sensor for CO₂ sensing. The XENSIV™ PAS CO2 is a real CO₂ sensor in an exceptionally small form factor based on the photoacoustic spectroscopy (PAS) principle.

Infineon's MEMS microphone, which is optimized for low-frequency operation, detects the pressure change generated by CO₂ molecules within the sensor cavity. CO₂ concentration is then delivered in the form of a direct ppm readout thanks to the integrated microcontroller. Highly accurate CO₂ readings are guaranteed.



Features

- **Operating range:** 0 ppm to 32000 ppm
- **Accuracy:** ± (30 ppm +3%) of reading between 400 ppm and 5000 ppm
- **Lifetime:** 10 years
- **Interface:** I2C, UART, and PWM
- **Package dimension:** 13.8 x 14 x 7.5 mm³
- **RoHs compliant**

Potential applications

High accuracy, compact size, and SMD capability make the XENSIV™ PAS CO2 ideal for indoor air quality monitoring solutions in the market with numerous potential applications.

- **HVAC (Heating, Ventilation, Air Conditioning)**
- **Home appliances**
- **Smart home IoT devices**
- **Agriculture/ Greenhouses**
- **In-cabin air quality monitoring unit**

Table 1 Order information of PASCO2V01

| OPN Number | SP Number | RoHS Compliant |
|----------------|-------------|----------------|
| PASCO2V01BUMA1 | SP005825756 | Yes |

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1 Block diagram

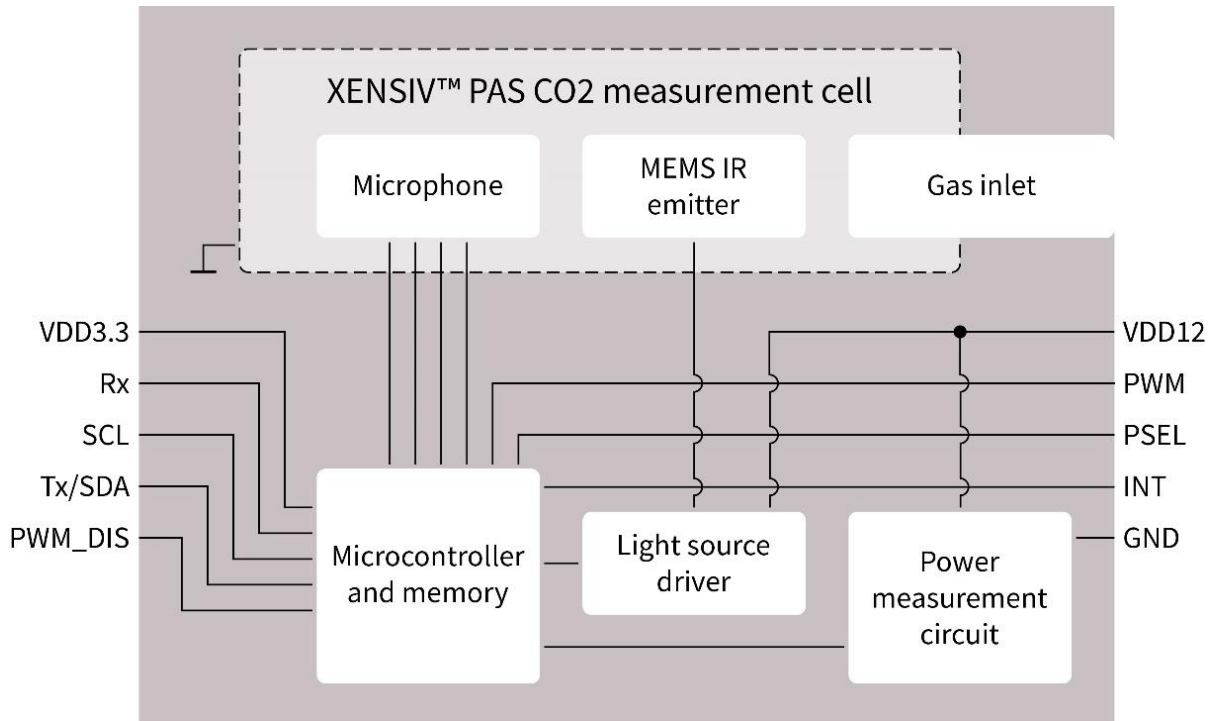


Figure 1 Block diagram of XENSIV™ PAS CO₂

2 Pin-out diagram

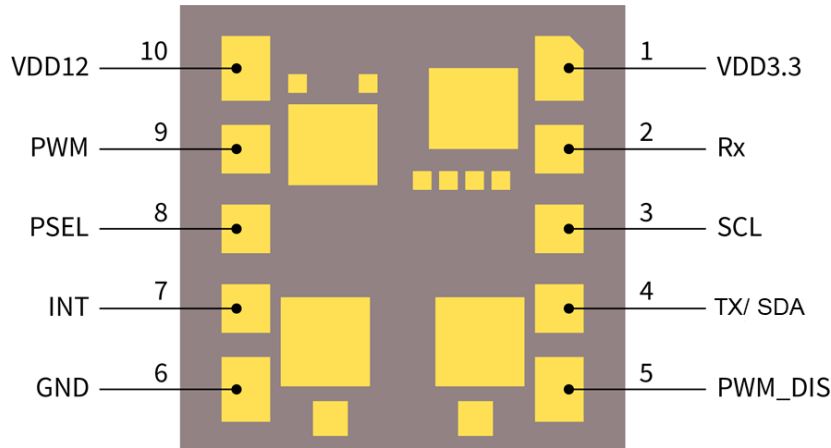


Figure 2 Pin-out diagram (Bottom view)

Table 2 Pin Description

| PIN | Symbol | Type | Description |
|-----|---------|---------------------|---|
| 1 | VDD3.3 | Power supply (3.3V) | 3.3V digital power supply |
| 2 | Rx | Input/ Output | UART receiver pin (3.3V domain) |
| 3 | SCL | Input/ Output | I2C clock pin (3.3V domain) |
| 4 | TX/ SDA | Output | UART transmitter pin (3.3V domain) / I2C data pin (3.3V domain) |
| 5 | PWM_DIS | Input | PWM disable input pin (3.3V domain) |
| 6 | GND | Ground | Ground |
| 7 | INT | Output | Interrupt output pin (3.3V domain) |
| 8 | PSEL | Input | Communication interface select input pin (3.3V domain) |
| 9 | PWM | Output | PWM output pin (3.3V domain) |
| 10 | VDD12 | Power supply (12V) | 12V power supply for the IR emitter |

3 The typical sensor response to the CO₂ concentration change

Measurement condition: VDD12 = 12V, VDD3.3=3.3V, T_{amb} = 25°C, P = 1013 hPa and %r.H. = 30%

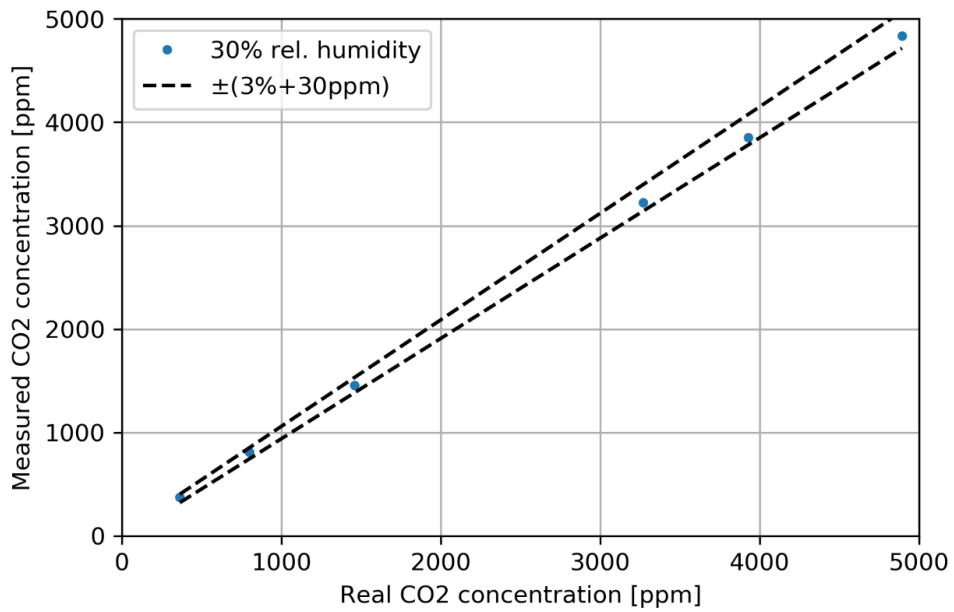


Figure 3 The typical sensor response to the CO₂ concentration change.

4 Characteristics and parameters

4.1 Specification

4.1.1 Operating condition

All parameters specified in the following sections refer to these operating conditions unless otherwise specified.

Table 3 Operating range

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|---|-------------------|--------|------|-------|------|--------------------------------|
| | | Min. | Typ. | Max. | | |
| CO ₂ measurement range ¹⁾ | C _{CO2} | 0 | | 32000 | ppm | Functional measurement range |
| Ambient temperature ¹⁾ | T _{amb} | 0 | | 50 | °C | |
| Relative humidity ¹⁾ | r.H. | 0 | | 85 | % | Non-condensing |
| Pressure ¹⁾ | p | 750 | 1013 | 1150 | hPa | |
| Supply voltage ¹⁾ | VDD3.3 | 3 | 3.3 | 3.6 | V | |
| | VDD12 | 10.8 | 12 | 13.2 | V | |
| Lifetime ¹⁾ | t _{life} | | 10 | | Year | Depends on the mission profile |

4.1.2 Storage condition

Storage condition refers to Dry pack: Packed, non-evacuated, desiccant²⁾, Humidity Indicator Card (HIC) sealed moisture barrier bag.

Table 4 Storage condition

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|--|--------------------------------|--------|------|------|------|-------------------------|
| | | Min. | Typ. | Max. | | |
| Storage temperature ¹⁾ | T _{storage} | 5 | | 40 | °C | <90% r.H. ³⁾ |
| Storage time ¹⁾ | t _{storage} | | | 1 | Year | |
| Storage temperature during transport ¹⁾ | T _{storage_transport} | -20 | | 60 | °C | |
| Storage time during transport ¹⁾ | t _{storage_transport} | | | 10 | Day | |

1) Not subject to production test. This parameter is verified by design/ characterization.

2) Number of desiccant units to be calculated according to JEDEC Standard 033.

3) Condensation and bedewing shall be avoided.

4.1.3 Timing characteristics

Table 5 Timing characteristics

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|--|--------------------------|--------|------|------|------|--|
| | | Min. | Typ. | Max. | | |
| Sampling time ¹⁾ | t_{sampling} | 5 | 60 | 4095 | s | Sensor accuracy might be reduced for sampling rates faster than 1 meas/ min. |
| Time to sensor ready ¹⁾ | $t_{\text{sensor_rdy}}$ | | | 1 | s | |
| Time to early notification ^{1), 2)} | $t_{\text{early_noti}}$ | | 2 | | s | |
| I2C Clock frequency ¹⁾ | f_{I2C} | | 100 | | kHz | |
| | | | 400 | | | |
| PWM frequency ¹⁾ | f_{pwm} | | 80 | | Hz | |
| UART baud rate ¹⁾ | f_{baud} | | 9.6 | | kBps | |

Typical measurement timing sequence has been illustrated in figure 4.

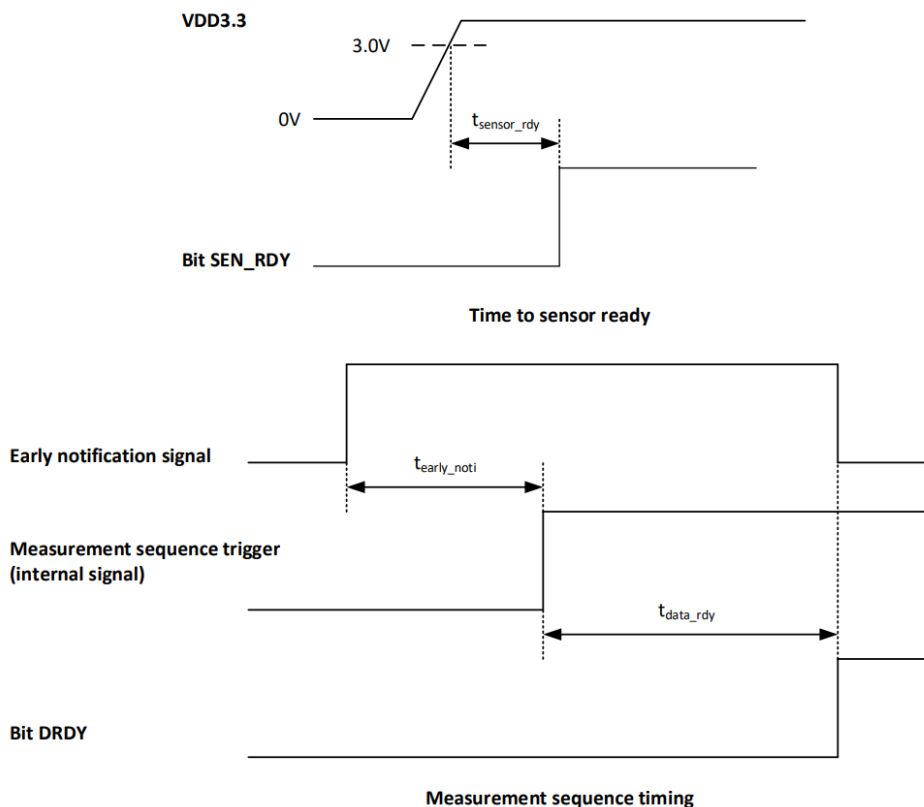


Figure 4 Illustration of the timing characteristic parameters

1) Not subject to production test. This parameter is verified by design/ characterization.

2) Relevant for continuous mode of operation.

4.1.4 Absolute maximum ratings

Table 6 Absolute maximum ratings¹⁾

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|-----------------------------|----------------------|--------|------|------|------|------------------------|
| | | Min. | Typ. | Max. | | |
| Moisture Sensitivity Level | MSL | | 3 | | | |
| Maximum ambient temperature | T _{amb_max} | -10 | | 60 | °C | |
| Maximum relative humidity | rH _{max} | 0 | | 95 | % | |
| 12V Supply voltage | V _{VDD12} | 9.6 | | 14.4 | V | |
| 3.3V Supply voltage | V _{VDD3.3} | 3.0 | | 3.6 | V | |
| Reflow temperature | T _r | | | 245 | °C | JEDEC J-STD-020E |
| ESD Human Body Model | V _{ESD_HBM} | -2 | | 2 | kV | HBM (JS001) |
| ESD Charge Discharge Model | V _{ESD_CDM} | | | 500 | V | CDM (JS002) |

Note: Stresses above the values listed as "Absolute Maximum Ratings" may cause permanent damage to the devices. Exposure to absolute maximum rating conditions for extended period of time may affect device reliability.

4.1.5 The current rating and power consumption

All parameters specified in the following sections refer to the operating conditions unless otherwise specified: VDD3.3 = 3.3V, VDD12 = 12V, T_{amb} = 25°C, % r.H. = 30 %, p = 1013 hPa.

Table 7 Current rating

| Parameter | Symbol | Pin | Values | | | Unit | Note or Test Condition |
|-------------------------------|-----------------------|--------|--------|------|------|------|------------------------|
| | | | Min. | Typ. | Max. | | |
| Peak current ¹⁾ | I _{peak 12} | VDD12 | | 130 | 150 | mA | |
| Peak current ¹⁾ | I _{peak 3.3} | VDD3.3 | | 10 | | mA | |
| Average current ¹⁾ | I _{avg 12} | VDD12 | | 0.8 | | mA | |
| Average current ¹⁾ | I _{avg 3.3} | VDD3.3 | | 6.1 | | mA | |
| Average power ¹⁾ | P _{avg} | | | 30 | | mW | |

Power consumption can be optimized further. For more details please refer to our application note section at the product [web page](#).

1) Not subject to production test. This parameter is verified by design/ characterization.

4.1.6 CO₂ Transfer Function

All parameters specified in the following sections refer to the operating conditions unless otherwise specified:

VDD3.3 = 3.3V, VDD12 = 12V, T_{amb} = 25°C, % r.H. = 30 %, p = 1013 hPa and t_{sampling} = 1 meas/ min.

Table 8 CO₂ Transfer Function

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|----------------------------------|----------------------|------------------------|-----|-----------------------|---------|---|
| | | Min. | Typ | Max. | | |
| Accuracy | Acc | -30 ppm- 3% of reading | | +30 ppm+3% of reading | ppm | C _{CO2} : 400 - 5000 ppm |
| Response time ¹⁾ | t ₆₃ | | 90 | | s | |
| Resolution ¹⁾ | Res | | 1 | | ppm | |
| Repeatability ^{1, 2)} | R | | | 10 | ppm | 3 times standard deviation at fixed C _{CO2} : 1000 ppm |
| Pressure stability ¹⁾ | p _{error} | | 0 | | %/hPa | With pressure compensation feature enabled |
| Drift ¹⁾ | d _{error} | | | 1 | %/ year | At 1 meas/ min with ABOC enabled in continuous mode |
| Acoustic stability ¹⁾ | SPL _{error} | 3 | 6 | 15 | ppm | Up to 95 dB for Pink noise from 100 Hz to 10 kHz |

1) Not subject to production test. This parameter is verified by design/ characterization.

2) Stepwise Reactive IIR filter is enabled.

4.2 Peripheral timing

4.2.1 I2C characteristics

Table 9 I2C Standard mode timing¹⁾

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|--|----------------|--------|------|------|------|------------------------|
| | | Min. | Typ. | Max. | | |
| Fall time of both SDA and SCL | t1 | | | 300 | ns | |
| Rise time of both SDA and SCL | t2 | | | 1000 | ns | |
| Data hold time | t3 | 0 | | | μs | |
| Data set-up time | t4 | 250 | | | ns | |
| LOW period of SCL clock | t5 | 4.7 | | | μs | |
| HIGH period of SCL clock | t6 | 4.0 | | | μs | |
| Hold time for a (repeated) START condition | t7 | 4.0 | | | μs | |
| Set-up time for (repeated) START condition | t8 | 4.7 | | | μs | |
| Set-up time for STOP condition | t9 | 4.0 | | | μs | |
| Bus free time between a STOP and START condition | t10 | 4.7 | | | μs | |
| Capacitive load for each bus line | C _b | | | 400 | pF | |

- 1) Due to the wired-AND configuration of an I2C bus system, the port drivers on the SCL and SDA signal lines need to operate in open-drain mode. The high level of these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbits/s, approximately 2 kOhm for operation at 400 kbits/s.

Table 10 I2C fast mode timing¹⁾

| Parameter | Symbol | Values | | | Unit | Note or Test Condition |
|--|-----------------|---------------------------|------|------|------|---|
| | | Min. | Typ. | Max. | | |
| Fall time of both SDA and SCL | t ₁ | 20 + 0.1 * C _b | | 300 | ns | C _b refers to the total capacitance of one bus line in pF. |
| Rise time of both SDA and SCL | t ₂ | 20 + 0.1 * C _b | | 300 | ns | C _b refers to the total capacitance of one bus line in pF. |
| Data hold time | t ₃ | 0 | | | μs | |
| Data set-up time | t ₄ | 100 | | | ns | |
| LOW period of SCL clock | t ₅ | 1.3 | | | μs | |
| HIGH period of SCL clock | t ₆ | 0.6 | | | μs | |
| Hold time for a (repeated) START condition | t ₇ | 0.6 | | | μs | |
| Set-up time for (repeated) START condition | t ₈ | 0.6 | | | μs | |
| Set-up time for STOP condition | t ₉ | 0.6 | | | μs | |
| Bus free time between a STOP and START condition | t ₁₀ | 1.3 | | | μs | |
| Capacitive load for each bus line | C _b | | | 400 | pF | |

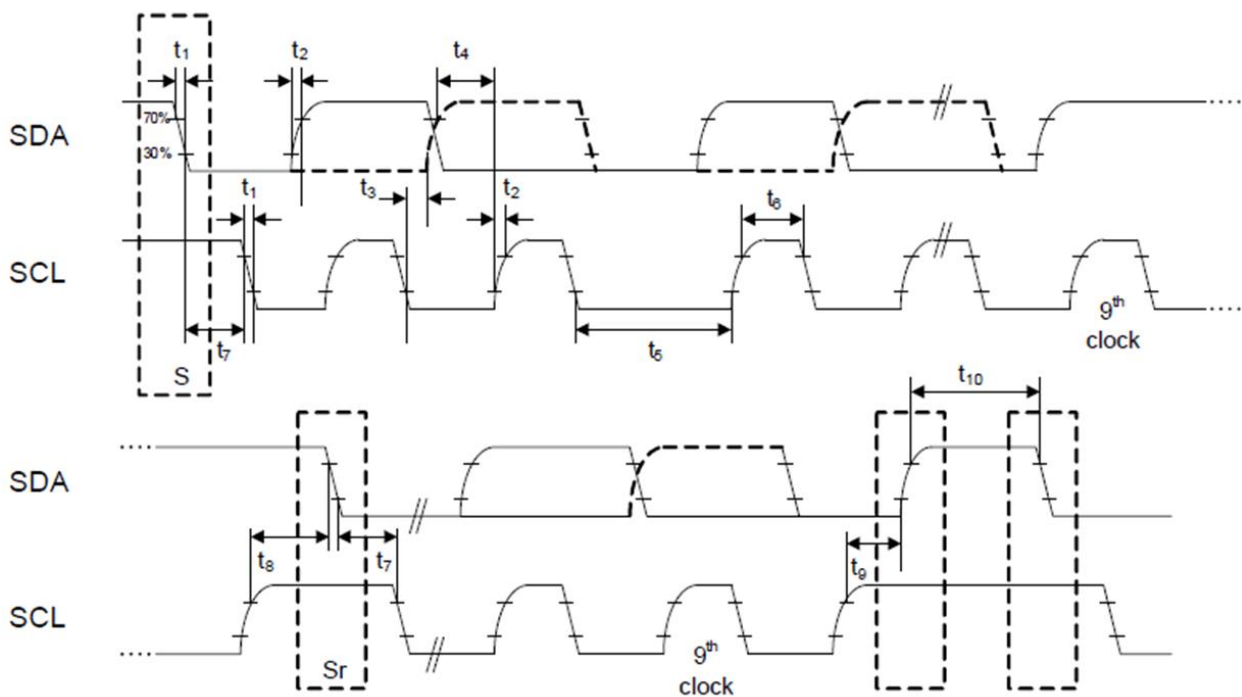


Figure 5 I2C Standard and Fast mode timing.

1) Due to the wired-AND configuration of an I2C bus system, the port drivers on the SCL and SDA signal lines need to operate in open-drain mode. The high level of these lines must be held by an external pull-up device, approximately 10 kOhm for operation at 100 kbits/s, approximately 2 kOhm for operation at 400 kbits/s.

4.2.2 UART characteristics

The main characteristics of the UART interface are described below:

- Point to point operation – no bus support.
- Slave operation only.
- $f_{baud} = 9.6 \text{ kBps}$
- Format: 1 start bit, 8 Data bits, no parity bit, 1 stop bit.
- Supports direct connection with terminal program.

For further details on UART and I2C communication protocol, please refer to our application note section in the product webpage.

4.3 Application Circuit Example

4.3.1 I2C application circuit example

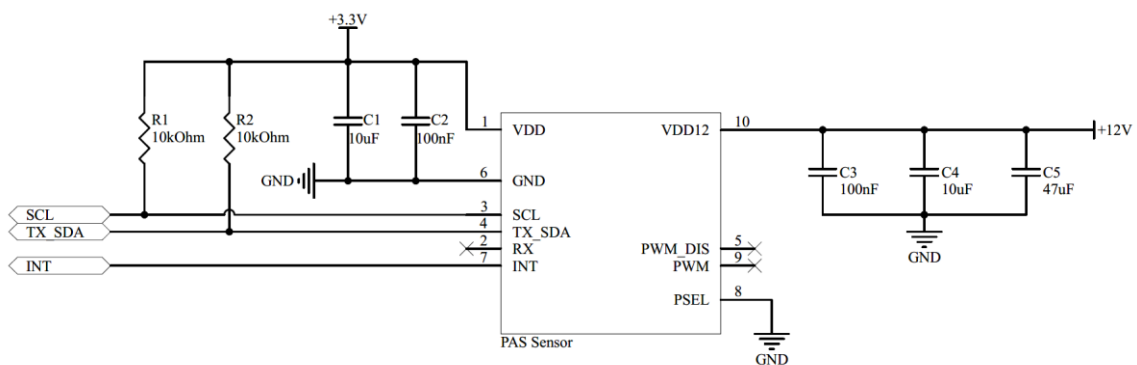


Figure 6 Application circuit example for I2C

With this configuration the device will start in idle mode of operation. Internal pull up is present on PWM_DIS pin.

4.3.2 UART application circuit example

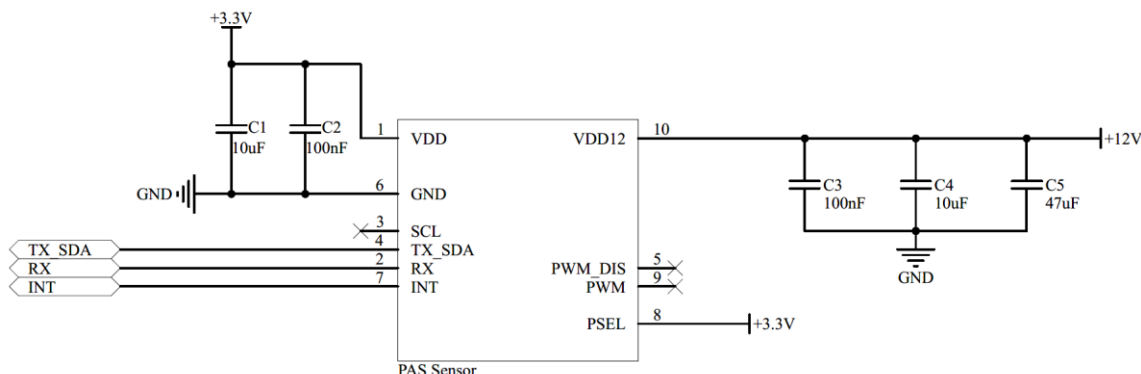


Figure 7 Application circuit example for UART

With this configuration the device will start in idle mode of operation. Internal pull up is present on PWM_DIS pin.

4.3.3 PWM application circuit example

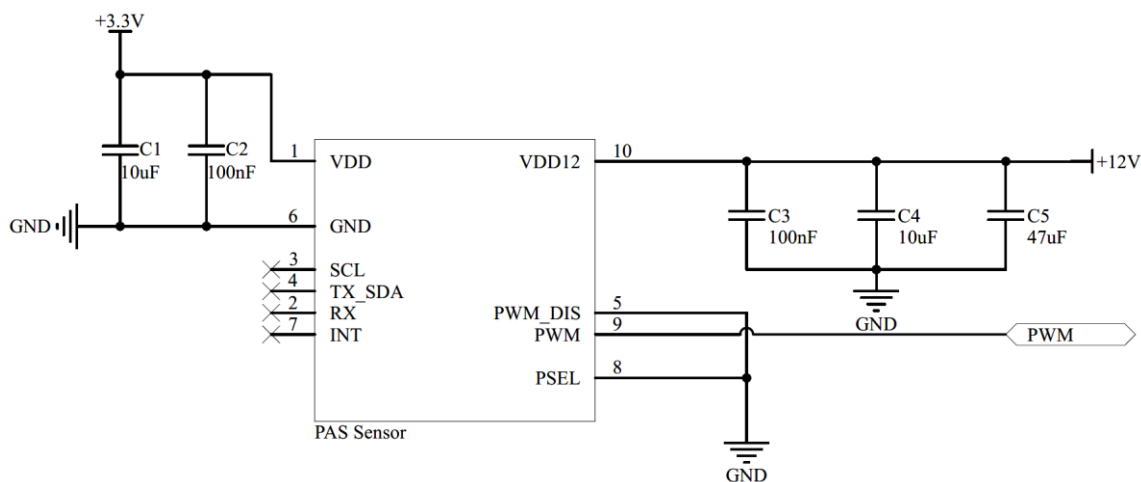


Figure 8 Application circuit example for PWM

4.4 Functional description

This section describes the operation of the sensor while measuring CO₂ concentrations. At any moment the device can be in one out of two different states: active and inactive. At active state, the CPU controlling the device is operating and can perform tasks such as: running a measurement sequence, serving an interrupt, etc. When the device has no specific task to perform, it goes to an inactive state. A transition from active to inactive state may occur at the end of a measurement sequence. In an inactive state, the CPU controlling the device is in sleep mode to optimize power consumption. Several events can wake up the device: the reception of a message on the serial communication interface, a falling edge on pin **PWM_DIS**, the internal generation of a measurement request in continuous measurement mode.

4.4.1 Operating Modes

The operating mode can be programmed via the serial communication interface by using the bit field **MEAS_CFG.OP_MODE**.

The sensor module supports three operating modes:

- **Idle mode:** The device does not perform any CO₂ concentration measurement. The device remains inactive until it becomes active shortly to serve interrupts before going back to an inactive state.
- **Continuous mode:** In this mode, the device periodically triggers a CO₂ concentration measurement sequence. Once a measurement sequence is completed, the device goes back to an inactive state and wakes up automatically for the next measurement sequence. The measurement period is programmable from 5 sec to 4095 sec.
- **Single-shot mode:** In this mode, the device triggers a single measurement sequence. At the end of the measurement sequence, the device goes back automatically to idle mode.

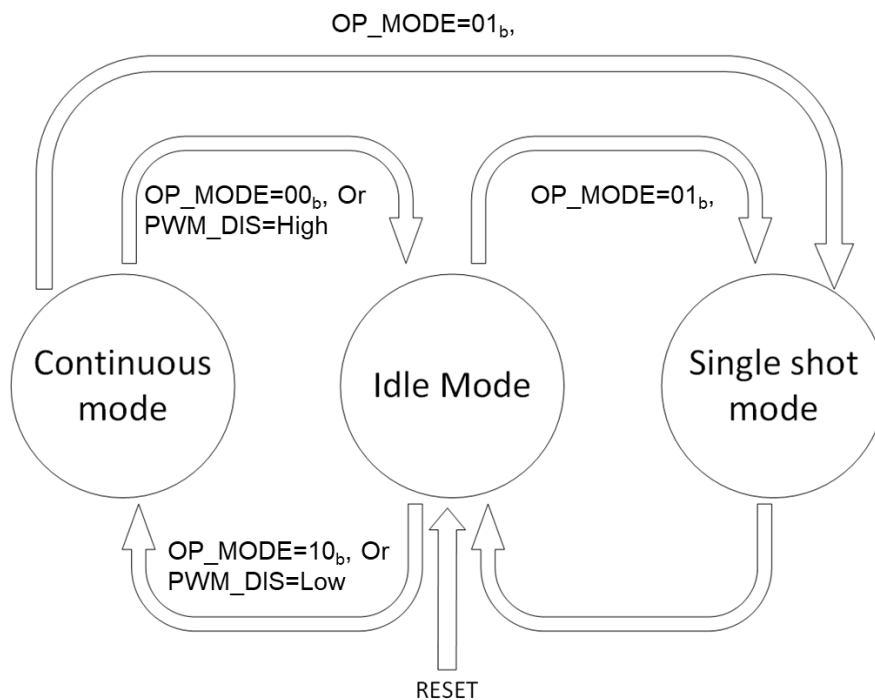


Figure 9 Operating mode transition

4.4.2 Data post-processing

Once the CO₂ concentration data has been acquired, several post-processing schemes can be applied to utilize different functionality.

4.4.2.1 Pressure compensation

The CO₂ concentration value acquired by the sensor is dependent on the external atmospheric pressure. To compensate for this effect, the application system can provide the value of the atmospheric pressure by writing into the specific registers, i.e. **PRESSREF_H** and **PRESSREF_L**. At the end of a measurement sequence, the device reads the pressure value and applies for compensation on the CO₂ concentration value before storing it into the result registers.

4.4.2.2 Automatic Baseline Offset Correction

To correct slow drifts caused by aging during operation, the device supports Automatic Baseline Offset Compensation. Every week of operation, the device computes an offset to correct the baseline of the device. The device must be in contact with the reference concentration (e.g. fresh air at 400 ppm of CO₂ concentration) at least 30 minutes per operating week to make sure proper baseline compensation. The device supports different configurations for compensation. **The ABOC setpoint may only be set between 350 and 1500 ppm.**

4.4.2.3 Forced compensation

Forced compensation provides a means to speed up the offset compensation process. Before forced compensation is enabled, the device shall be physically exposed to the reference CO₂ concentration. The device will use the **3 next measurements to calculate the compensation offset**. The user shall ensure constant exposure to the reference CO₂ concentration during that time. **It is recommended to operate at 1 measurement per 10 seconds while implementing the forced compensation scheme.** When 3 measurement sequences are completed, the device automatically reconfigures itself with the newly computed offset applied to the subsequent CO₂ concentration measurement results.

4.4.2.4 Alarm Threshold

The device can be configured via interrupt to perform an alarm threshold check each time a new CO₂ concentration data is acquired. At the end of each measurement sequence, the computed CO₂ value (after all applicable offset compensations) is compared to the concatenated value in **ALARM_TH_H** and **ALARM_TH_L**. In case of a threshold violation, the sticky bit **MEAS_STS.ALARM** is set. This also sets pin **INT** to active level due to configuration as alarm. Bit **MEAS_STS.ALARM** is cleared by reading register **MEAS_STS.ALARM_CLR**.

4.5 Monitoring mechanism as advanced functionality

The device supports several mechanisms to monitor the correct operation of the sensor.

Table 11 **Functionality description**

| Mechanism | Description |
|-----------------------------------|--|
| Sensor Ready status | After each power-on reset, bit SENS_STS.SEN_RDY is set to confirm that the sensor has initialized correctly. |
| Scratchpad register | <p>To check the integrity of the communication layer of the serial communication interface, register SCRATCH_PAD can be used. This register can use this memory field to write any value and verify that the data received by the device is correct.</p> <p>It can also be used to verify that a soft reset has been executed, using the following sequence:</p> <ol style="list-style-type: none"> 1. The user writes a non-default value to register SCRATCH_PAD. 2. The user reads back register SCRATCH_PAD to verify the writ commend has been correctly executed. 3. The user writes register SENS_RST to trigger a soft reset. 4. The user reads register SCRATCH_PAD to verify that it has been reset to its default value. |
| VDD12V verification | At power-up and the beginning of each measurement sequence, the device measures automatically the voltage at VDD12 . If the measured voltage exceeds the specified operating range of the device, bit SENS_STS.ORVS is set. The measurement sequence is however completed normally. Bit SENS_STS.ORVS can be cleared by setting bit SENS_STS.ORVS_CLR |
| Internal temperature verification | At the beginning of each measurement sequence, the device measures automatically its internal temperature. If the measured temperature exceeds the specified operating ranged of the device, sticky bit SENS_STS.ORTMP is set. The measurement sequence is however completed normally. Bit SENS_STS.ORTMP can be cleared by setting bit SENS_STS.ORTMP_CLR . |

4.6 Digital interface

The XENSIV™ PAS CO2 supports I2C, UART, and PWM. The communication protocols have been covered in separate application notes.

4.6.1 I2C interface

The device complies with the I2C protocol. When I2C is selected as a serial communication interface, the device acts as an I2C slave. The main characteristics of the interface are described below:

- Slave mode only.
- I2C Clock frequency: 100 kHz and 400 kHz
- 7-bit slave address: 0x28
- No CRC.
- The device supports clock stretching.
- 8bit addressing mode supported (7bit address + RW)
- Bulk read and write supported (device auto-increments automatically the address).
- Address 0x00 not supported.

Further details of the protocol are covered in the separate application note.

4.6.2 I2C transaction format

The I2C transaction has the following structure: a start condition followed by four bytes followed a stop condition.

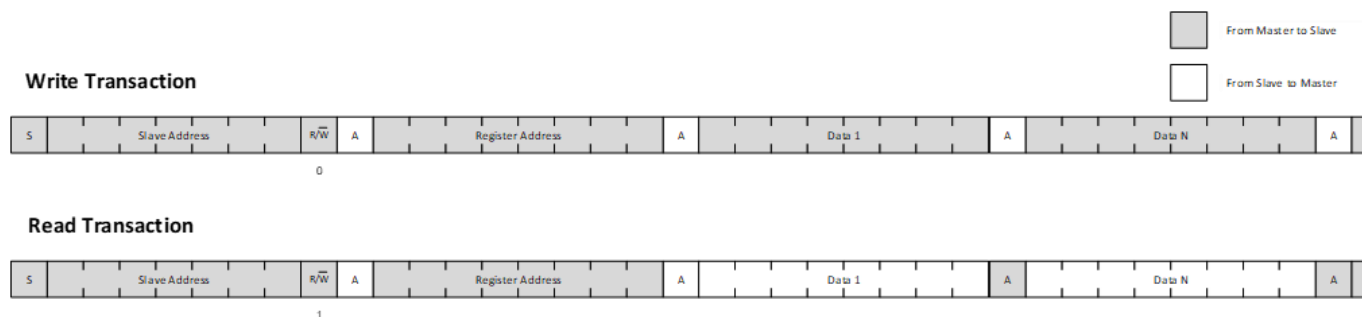


Figure 10 I2C write and read transaction

Table 12 I2C transaction

| Byte | Description | Value | Comments |
|------|-----------------|------------------------------------|--|
| | Start condition | | |
| 1 | Header | (Slave Address << 1) R/W | |
| 2 | First data-byte | As per user request/register value | Read: data provided by the slave Write: data provided by the user |
| N+2 | Data byte N | As per user request/register value | Read: data provided by the slave Write: data provided by the user |
| | End condition | | |

4.6.3 UART Interface

When UART is selected as a serial communication interface, the device acts as a UART slave. The device operates via UART for point-to-point communication. Bus operation is not supported. As a result, it is recommended that the master uses a time-out mechanism. The basic format of a valid UART frame is 1 start bit, 8 data bits, no parity bit, and 1 stop bit. The master combines several UART frames into a message (read or write). The combination of master request and slave answer defines a transaction. The main characteristics of the interface are described below:

- Point to point operation – no bus support.
- Slave operation only.
- UART clock frequency = 9.6 kHz
- Format: 1 start bit, 8 Data bits, no parity bit, 1 stop bit. Supports direct connection with a terminal program.

For further details on UART communication, please have a look into our relevant application note titled as 'Programming guide for XENSIV™ PAS CO₂' in the application note section on the product website.

4.7 Register map

| Name | Address | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | Reset | |
|-------------|---------------------|--|------------------|----------------|----------------|----------------|------------------|----------------|-----------------|-------|------|
| PROD_ID | 0x00 | PROD r | | | REV r | | | | | | 0x4F |
| SENS_STS | 0x01 | SEN_RDY rh | PWM_DIS_ST rh | ORTMP rhs | ORVS rhs | ICCER rhs | ORTMP_CLR w | ORVS_CLR w | ICCER_CLR w | 0xC0 | |
| MEAS_RATE_H | 0x02 | VAL rwh | | | | | | | | | 0x00 |
| MEAS_RATE_L | 0x03 | VAL rwh | | | | | | | | | 0x3C |
| MEAS_CFG | 0x04 | 0 rw | PWM_OUTEN rw | PWM_MODE rw | BOC_CFG rwh | | | OP_MODE rwh | | 0x24 | |
| CO2PPM_H | 0x05 | VAL r | | | | | | | | | 0x00 |
| CO2PPM_L | 0x06 | VAL r | | | | | | | | | 0x00 |
| MEAS_STS | 0x07 | 0 rw | Res rh | DRDY rhs | INT_STS rhs | ALARM rhs | INT_STS_CLR w | ALARM_CLR w | | 0x00 | |
| INT_CFG | 0x08 | 0 rw | | | INT_TYP rw | INT_FUNC rw | | | ALARM_TYP rw | 0x11 | |
| ALARM_TH_H | 0x09 | VAL rw | | | | | | | | | 0x00 |
| ALARM_TH_L | 0x0A | VAL rw | | | | | | | | | 0x00 |
| PRESS_REF_H | 0x0B | VAL rwh | | | | | | | | | 0x03 |
| PRESS_REF_L | 0x0C | VAL rwh | | | | | | | | | 0xF7 |
| CALIB_REF_H | 0x0D | VAL rwh | | | | | | | | | 0x01 |
| CALIB_REF_L | 0x0E | VAL rwh | | | | | | | | | 0x90 |
| SCRATCH_PAD | 0x0F | VAL rw | | | | | | | | | 0x00 |
| SENS_RST | 0x10 | SRTRG w | | | | | | | | | 0x00 |
| Reserved | 0x11 ... 0x14 | Reserved registers Read & Write access to those registers generate a communication error | | | | | | | | | |
| Reserved | 0x15 ... 0xFF | Reserved registers Read & Write access to those registers generate a non-acknowledge condition. | | | | | | | | | |

Complete 'Register-map description' has been covered in a separate application note titled as 'Register-map description of XENSIV™ PAS CO2' in the product webpage.

5 Assembly instruction

XENSIV™ PAS CO2 module is classified as Moisture-Sensitivity Level 3 (MSL 3). The maximum reflow temperature during board assembly must not exceed 245°C according to IPC/JEDEC J-STD-020E. As shown in the figure 13, Pad 1 to 14 need to be soldered. Pad 1 to 10 need to be assembled as per functionality. Pad 11 and 13 need to be connected to the GND. Pad 12 and 14 are not internally connected but must be soldered to maintain mechanical stability. Pad 12 and 14 can be left open or connected to GND. Non-marked smaller pads should be kept open.

Further details such as footprint drawing, board assembly guidelines, stencil recommendation can be found into CO2 product page under Infineon package name '[LG-MLGA-14](#)'.

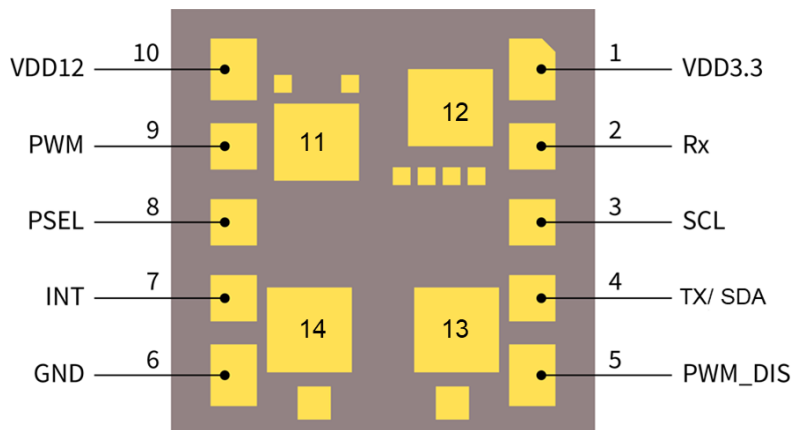


Figure 11 XENSIV™ PAS CO2 pads need to be connected to an application board.

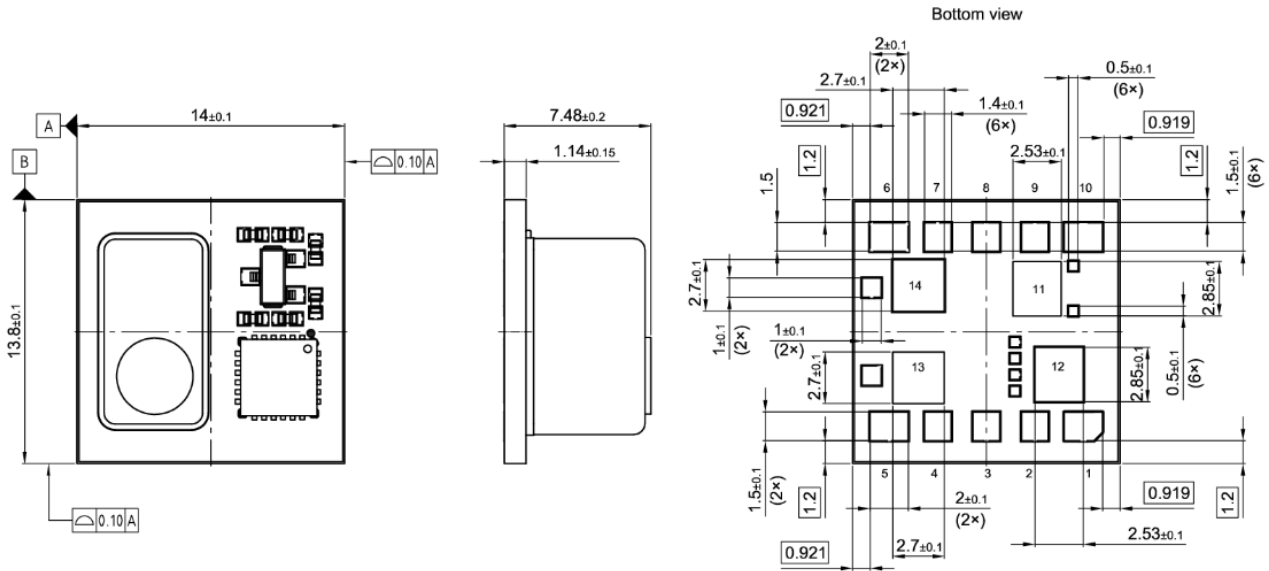
Note: 1) One-time reflow is permitted and after assembly rework is not recommended.
 2) Vapor phase soldering may damage the sensor irreversibly.

For the customer, the allocated floor time (Out of bag) is 168 hours (at ≤30°C and 60% r.H.) according to IPC/JEDEC J-STD-020. If floor time exceeds, then the parts (Out of moisture barrier bag) need to be baked according to the following table:

Table 13 Baking condition of the XENSIV™ PASCO2

| Package condition | Bake temperature | Bake time | Condition |
|-------------------------|------------------|-----------|-----------|
| Sensors outside of tape | 125°C | 24 hours | r.H. < 5% |
| Sensors within the tape | 40°C | 8 days | r.H. < 5% |

6 Package information

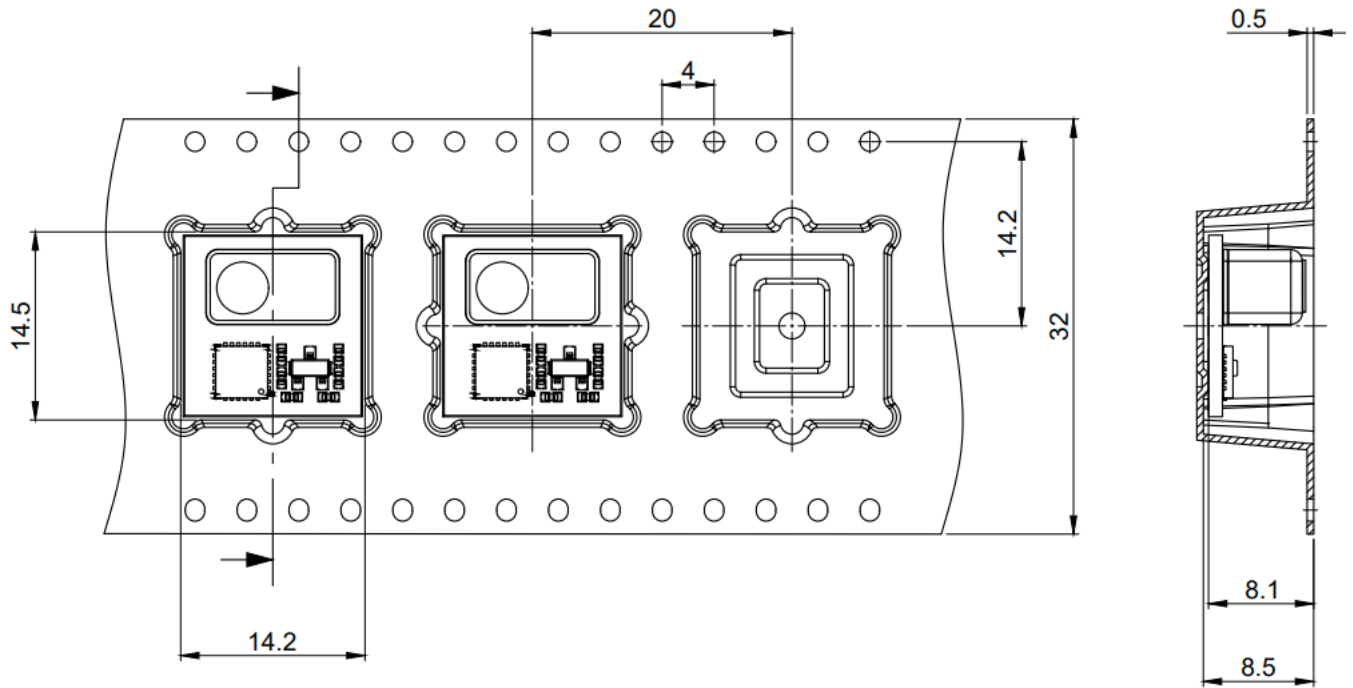


All dimensions are in units mm
 The drawing is in compliance with ISO 128-30, Projection Method 1 []
 Drawing according to ISO 8015, general tolerances ISO 2768-mK

Figure 12 Package dimensions of XENSIV™ PAS CO₂.

7 Packing for shipment

The device will be shipped in tape and reel. Each tape and reel consist of 300 parts.



All dimensions are in units mm
The drawing is in compliance with ISO 128-30, Projection Method 1 []

Figure 13 Tape and reel packing of XENSIV™ PAS CO₂

8 Revision history

Table 14 Datasheet versions tracking

| Reference | Description | Date |
|-----------|--|------------|
| 0.1 | First copy of the preliminary datasheet | 13.10.2020 |
| 0.2 | Second copy of the preliminary datasheet | 25.06.2021 |
| 1.0 | First release of the datasheet | 17.01.2022 |
| 1.1 | Updated Storage condition, assembly instruction and minor cosmetic changes | 13.06.2022 |
| 1.2 | Storage during transportation, resolved ambiguity before paragraph 4.1.5, updated the baking time in assembly instruction and minor cosmetic changes | 21.09.2022 |
| 1.3 | Correction made in Storage condition section (non-evacuated instead of evacuated dry-pack). Note on typical sampling rate and sensor performance added. Parameter resolution added | 21.11.2022 |